

Dag R Andersson

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3464579/publications.pdf>

Version: 2024-02-01

21
papers

192
citations

1684188

5
h-index

1474206

9
g-index

22
all docs

22
docs citations

22
times ranked

210
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of PCB cracks on thermal cycling reliability of passive microelectronic components with single-grained solder joints. <i>Microelectronics Reliability</i> , 2019, 93, 61-71.	1.7	23
2	Smart access to small lot manufacturing for systems integration. , 2018, , .		0
3	Quality assurance of encapsulation architecture, including subsequent washing process for permanently mounted wearable sensors. , 2018, , .		0
4	On the formation and propagation of laminate cracks and their influence on the fatigue lives of solder joints. , 2018, , .		3
5	SMARTER-SI - Smart access to manufacturing for Systems Integration. , 2017, , .		1
6	Simulations of the impact of single-grained lead-free solder joints on the reliability of ball Grid Array components. , 2017, , .		8
7	Thermal Simulations and Experimental Verification of Power Modules Designed for Double Sided Cooling. , 2016, , .		2
8	COSIVU " Compact, smart and reliable drive unit for fully electric vehicles. , 2016, , .		5
9	Thermo-mechanical simulations of SiC power modules with single and double sided cooling. , 2015, , .		5
10	Model verification of heat exchangers in a flow test rig. , 2015, , .		0
11	The shear strength of nano-Ag sintered joints and the use of Ag interconnects in the design and manufacture of SiGe-based thermo-electric modules. <i>Microelectronics Reliability</i> , 2015, 55, 722-732.	1.7	10
12	Multiphysics study of RF/microwave planar devices: Effect of the input signal power. , 2014, , .		12
13	Modeling of SiC power modules with double sided cooling. , 2014, , .		1
14	The shear strength of nano-Ag solders and the use of Ag interconnects in the design and manufacture of SiGe-based thermo-electric modules. , 2014, , .		0
15	UML modelling concepts of HAZOP to enhance the ability to identify emerging risks. <i>Journal of Risk Research</i> , 2013, 16, 421-432.	2.6	3
16	Current Problems and Possible Solutions in High-Temperature Lead-Free Soldering. <i>Journal of Materials Engineering and Performance</i> , 2012, 21, 629-637.	2.5	68
17	Thermo-mechanical simulations and measurements on high temperature interconnections. , 2011, , .		1
18	Thermal Cycling Aging Effect on the Shear Strength, Microstructure, Intermetallic Compounds (IMC) and Crack Initiation and Propagation of Reflow Soldered Sn-3.8Ag-0.7Cu and Wave Soldered Sn-3.5Ag Ceramic Chip Components. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008, 31, 331-344.	1.3	21

#	ARTICLE	IF	CITATIONS
19	Printed circuit boards for lead-free soldering: materials and failure mechanisms. Circuit World, 2007, 33, 10-16.	0.9	4
20	Effect of different temperature cycling profiles on the crack initiation and propagation of Sn-3.5Ag wave soldered solder joints. Microelectronics Reliability, 2007, 47, 266-272.	1.7	1
21	Significance of intermediate production processes in life cycle assessment of electronic products assessed using a generic compact model. Journal of Cleaner Production, 2005, 13, 1269-1279.	9.3	22